# LIGHT EMITTING DIODE SPECIFICATION

DESCRIPTION: E6C0606RVGC2-A02AA-0.60T-RG01

REVISION: V2.2

ISSUE DATE: 2019-04-03

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Red-Green



#### Features:

- Long operating life
- •Low Power Consumption
- Wide Viewing Angle
- •Low voltage DC operated
- ●RoHS Compliant

### **Application:**

- Backlight
- Decoration lighting
- motormeter
- Indicator



AlGaInP-InGaN

### Electro-Optical Characteristics(Ta=25°C, @20mA)

E6C0606RVGC2-A02AA-0.60T-RG01

Parameter	Color	Symbol	Min.	Тур.	Max.	Unit
			70	100	150	
Luminous Intensity		IV	400	500	800	mcd
			-	20	-	
Radiation Bandwidth		$\triangle \lambda$	-	35	-	nm
			1.90	2.00	2.40	
Forward Voltage		VF	2.90	3.00	3.40	v
			617	620	626	
Dominant Wavelength		λd	517	520	530	nm
Viewing Angle	-	201/2	-	120	-	deg
Reverse Current	-	IR	-	-	10	uA

### Absolute Maximum Ratings(Ta=25℃)

Parameter Parame	Symbol	Max.	Unit
Peak Forward Current(1/10 Duty Cycle, 0.1ms Pulse Width)	IFP	100	mA
Forward Current	IF	20	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge	ESD	2000	V
Operating Temperature Range	Topr	-40to+90	°C
Storage Temperature Range	Tstg	-40to+90	°C
Reflow Soldering	Tsld	260°C for 10secs	

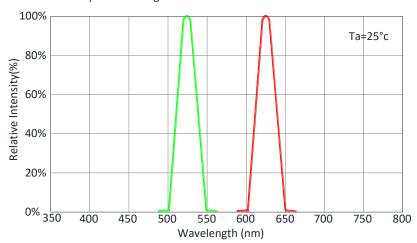


Water Clear

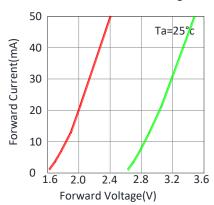


## **Optical & Electrical Characteristics**

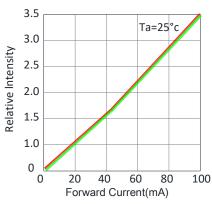




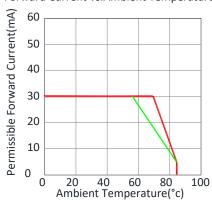
#### Forward Current vs.Forward Voltage



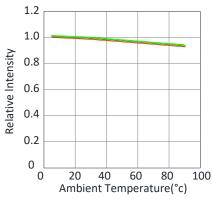
Relative Intensity vs.Forward Currenr

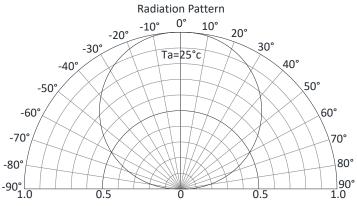


Forward Current vs. Ambient Temperature



Relative Intensity vs. Ambient Temperature







## **Reliability** Test Items And Conditions

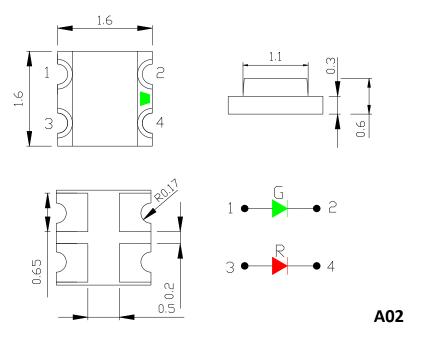
Test Items	Reference	<b>Test Conditions</b>	Time	Quantity	Criterion
Thermal Shock	MIL-STD-202G	-40°C (30min) -100°C (30min)	100 Cycles	22	0/22
Temperature And Humidity Cyclic	JEITA ED-4701 200 203	-10℃~65℃; 0%~90%RH	10cycles	22	0/22
High Temperature Storage	JEITA ED -4071 200 201	Ta=100℃	1000H	22	0/22
Low Temperature Storage	JEITA ED -4071 200 202	Ta=-40°C	1000H	22	0/22
High Temperature High Humidity Storage	JEITA ED -4071 100 103	Ta=60℃; RH=90%	1000H	22	0/22
High Temperature Life Test	JESD22-A108D	Ta=80 ℃	1000H	22	0/22
Life Test	JESD22-A108D	Ta=25℃ IF=5mA	1000H	22	0/22
Resistance to Sodering Heat	GB/T 4937, II , 2.2&2.3	Tsol*=(240±5) °C10secs	2 times	22	0/22

# **Criteria For Judging Damage**

Test Items	Symbol	<b>Test Conditions</b>	Criteria For Judging Damage
Forward Voltage	$V_{F}$	I <sub>F</sub> =I <sub>FT</sub>	Initial Data±10%
Recerse Current	$I_R$	V <sub>R</sub> =5V	I <sub>R</sub> ≤10uA
Luminous Intensity	IV	I <sub>F</sub> =I <sub>FT</sub>	Average I <sub>V</sub> degradation≤30%; Single LED I <sub>V</sub> degradation≤50%
Resistance to Soldering Heat	-	-	Meterial without internal cracks,no meterial between stripped,no deaded light



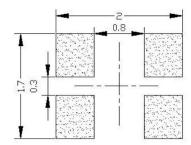
## **Product size (Unit:mm)**



#### NOTES:

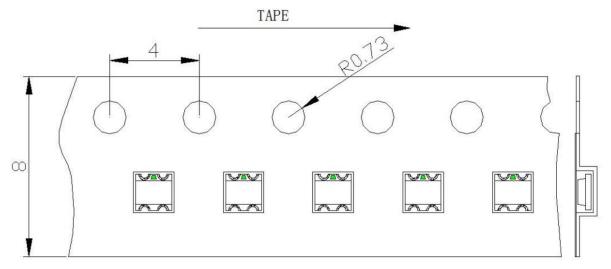
- 1. All dimensions are in millimeters (inches)
- 2. Tolerances are  $\pm 0.2 \text{mm}$  (0.008inch) unless otherwise noted

### Recommended Soldering Pad Design (Unit:mm)



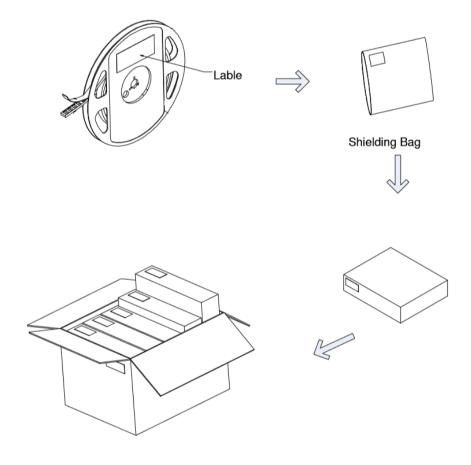
## Taping and package Spec

●Tape Specification:3,000pcs Per Reel





## **Packaging**



## LabelStyle

EKINGLUX OPTOELECTRONICS(SHANGHAI) CO.,LTD

TEL:86 21 59909181

Sales@ekingluxs.com

P/N:XXXXXXXXXXXXXXXX

**Emitting Color: XXXX** 

HUE: XXX-XXX nm

IV: XXX-XXX mcd **example** 

VF: XX-XX V BIN Code: XX

QTY: XX PCS DATE: XXXX/XX/XX

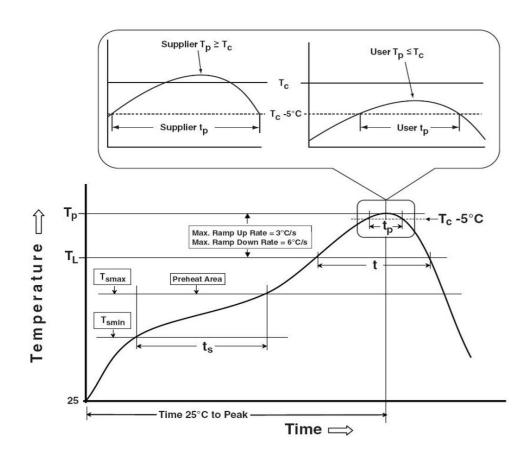
LOT NO.:XXXXXXX



### **Table of Classification Reflow Profiles**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly	
Preheat & Soak	100 °C	150 °C	
Temperature min (Tsmin)	150°C	200 °C	
Temperature max (Tsmax)	60-120 seconds	60-120 seconds	
Time (Tsmin to Tsmax) (ts)			
Average ramp-up rate (Tsmax to Tp)	3 °C/second max	3 °C/second max	
Liquidous temperature (TL)	183 °C	217 °C	
Time at liquidous (tL)	60-150 seconds	60-150 seconds	
Peak package body temperature (Tp)*	230 °C ~235 °C	255 °C ~260 °C	
Classification temperature (Tc)	235 °C	260 °C	
Time (tp) within 5 °C of the specified	20 seconds	30 seconds	
Classification temperature (Tc)			
Average ramp-down rate (Tp to Tsmax)	6 °C/second max	6 °C/second max	
Time 25 °C to peak temperature	6 minutes max	8 minutes max	

- 1. Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.
- 2. Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.





#### **Precautions**

#### 1. Storage:

- •Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to aminimum.
- ullet Before opening the package, the product should be kept at 30°C or less and humidity less than 60% RH, and beused within a year.
- •After opening the package, the product should be stored at 30°C or less and humidity less than 10%RH. It is recommended that the product be operated at the workshop condition of 30°C or less and humidity less than 60%RH.
- •If the moisture absorbent material has fade away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: (70±5)°C for 24 hours.

#### 2. Static Electricity:

Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristic such as the forward voltage becomes lower, or the LEDs do not light at the low current. even not light.

All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.

#### 3. Vulcanization:

LED curing is due to sulfur being in bracket and the +1 price of silver in the chemical reaction generated Ag2S in the process. It will lead to the capacity of reflecting of silver layer reducing, light color temperature drift and serious decline ,seriously affecting the performance of the product. So we should take corresponding measures to avioding vulcanization, such as to avoid using sulphur volatile substances and keeping away from high sulphur content of the material.